SDAS278 - JANUARY 1995

- Bidirectional Bus Transceivers in High-Density 20-Pin Packages
- True Logic
- 3-State Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

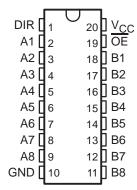
description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

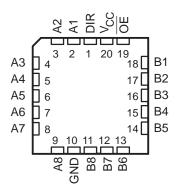
The -1 version of the SN74ALS645A is identical to the standard version, except that the recommended maximum I_{OL} is increased to 48 mA. There is no -1 version of the SN54ALS645A.

The SN54ALS645A and SN54AS645 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS645A and SN74AS645 are characterized for operation from 0°C to 70°C.

SN54ALS645A, SN54AS645 . . . J PACKAGE SN74ALS645A, SN74AS645 . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS645A, SN54AS645 . . . FK PACKAGE (TOP VIEW)



FUNCTION TABLE

INP	UTS	ODED ATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

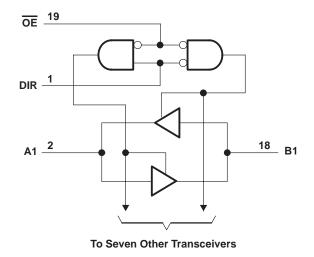
SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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logic symbol†

OE DIR 3 EN1 [BA] 3 EN2 [AB] 18 В1 \triangleright 2 ▽ 17 B2 16 **A3 B3** 15 **B**4 Α4 14 Α5 **B5** 13 **B6** A6 12 Α7 **B7** 11 **A8 B8**

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Input voltage, V _I : All inputs	
I/O ports	5.5 V
Operating free-air temperature range, TA: SN54A	LS645A –55°C to 125°C
SN74A	LS645A 0°C to 70°C
Storage temperature range	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SNS	54ALS64	5A	SN74ALS645A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vсс	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
loh	High-level output current			-12			-15	mA
la.	Low lovel output ourrent			12			24	mA
IOL	Low-level output current						48§	IIIA
TA	Operating free-air temperature	-55		125	0		70	°C

[§] Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645 **OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS**

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST CON	IDITIONS	SN5	4ALS64	5A	SN7	74ALS64	5A	UNIT
	PARAMETER	TEST CON	IDITIONS	MIN	TYP [†]	MAX	MIN	TYP	MAX	UNII
٧ıĸ		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2)		V _{CC} -2	2		
\/a			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH		V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V
			$I_{OH} = -15 \text{ mA}$				2			
			I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL		V _{CC} = 4.5 V	$I_{OL} = 24 \text{ mA}$					0.35	0.5	V
			$I_{OL} = 48 \text{ mA}^{\ddagger}$					0.35	0.5	
1.	Control inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1			0.1	mA
11	A or B ports	vCC = 3.3 v	V _I = 5.5 V			0.1			0.1	IIIA
	Control inputs	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
lін	A or B ports§	VCC = 5.5 V,	V = 2.7 V			20			20	μΑ
1	Control inputs	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
IIL	A or B ports§	VCC = 5.5 V,	V = 0.4 V			-0.1			-0.1	IIIA
Io¶		$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		30	48		30	0 45	
ICC		V _{CC} = 5.5 V	Outputs low		36	60		36	55	mA
			Outputs disabled		38	63		38	58	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R1 R2	_ = 50 pF l = 500	2,	,	UNIT
			SN54AL	S645A	SN74AL		
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	D A	1	19	3	10	ns
t _{PHL}	AUID	B or A	1	14	3	10	115
^t PZH	ŌĒ	A D	2	30	5	20	ns
t _{PZL}	OE	A or B	2	29	5	20	115
^t PHZ	ŌĒ	A or B	2	14	2	10	ne
t _{PLZ}	OE .	AUIB	2	30	4	15	ns

[#] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



 $[\]ddagger$ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V § For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645 **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, T _A : SN54AS645	55°C to 125°C
SN74AS645	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

		SN54AS645		5	SN74AS645			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-12			-15	mA
lOL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEOT 001	IDITIONS	SN	154AS64	15	SN	174AS64	15	UNIT	
	PARAMETER	IEST CON	TEST CONDITIONS		TYP‡	MAX	MIN	TYP [‡]	MAX	ONII	
٧ıK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2				
\/ a			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V	
VOH		V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.4						V	
			$I_{OH} = -15 \text{ mA}$				2.4				
\/a:		V _{CC} = 4.5 V	I _{OL} = 48 mA		0.3	0.55				V	
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$					0.35	0.55	V	
1.	Control inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1			0.1	mA	
11	A or B ports	VCC = 5.5 V	V _I = 5.5 V			0.1			0.1	IIIA	
l	Control inputs	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μА	
ΙΗ	A or B ports§	VCC = 3.3 v,	V = 2.7 V			70			70	μΑ	
1	Control inputs	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.5			-0.5	mA	
ΊL	A or B ports§	VCC = 5.5 v,	V = 0.4 V		-0.75		-(-0.75	IIIA	
IOI		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.25 \text{ V}$	-50		-150	-50		-150	mA	
			Outputs high		62	97		62	97		
ICC		V _{CC} = 5.5 V	Outputs low		95	149		95	149	mA	
			Outputs disabled		79	123		79	123		

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

SN54ALS645A, SN54AS645, SN74ALS645A, SN74AS645 **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS SDAS278 – JANUARY 1995

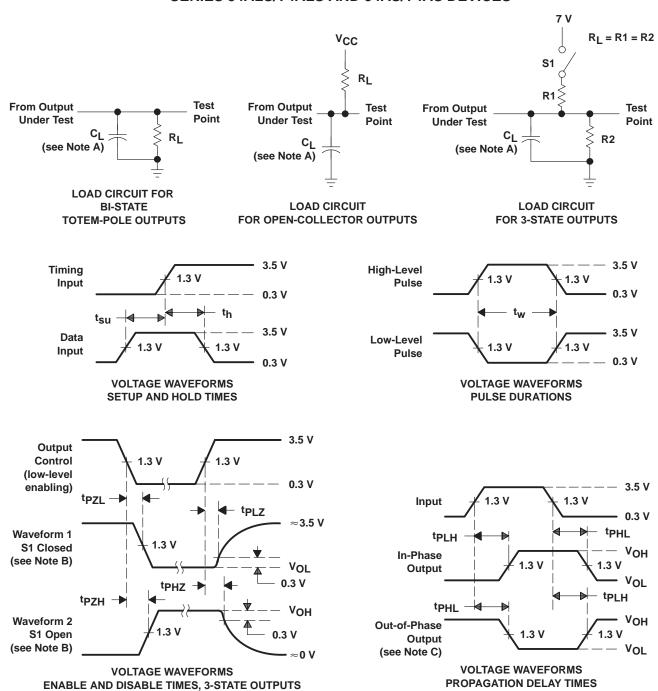
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R1 R2 T _A	= 50 pF = 500 Ω = 500 Ω = MIN t	2, 2, o MAX†		UNIT
			SN54A	S645	SN74A		
			MIN	MAX	MIN	MAX	
^t PLH	A or B	D A	2	11	2	9.5	ns
^t PHL	AOID	B or A	2	10.5	2	9	113
^t PZH	ŌĒ	A D	2	12	2	11	ns
^t PZL	OE .	A or B	2	12	2	10	115
t _{PHZ}	ŌĒ	A or B	2	8	2	7	nc
t _{PLZ}	OE .	AUIB	2	13	2	12	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84033012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8403301RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
8403301SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN54ALS645AJ	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54AS645J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS645A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS645A-1N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS645A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS645A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645A-1NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS645AN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS645ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS645ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS645ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM





nm 18-Sep-2008

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74ALS645ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS645DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS645DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS645DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS645DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS645DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS645DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS645N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS645NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ALS645AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS645AJ	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54ALS645AW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54AS645FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54AS645J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AS645W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



PACKAGE OPTION ADDENDUM

18-Sep-2008

In no event shall Ti's	liability arising out of	such information ex	ceed the total pure	chase price of the	TI part(s) at issue	in this document s	sold by TI
In no event shall TI's to Customer on an ar	nnual basis.			onace phote of the	Tripani(o) an local		



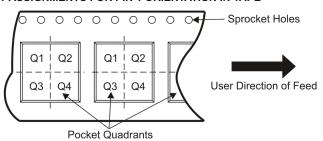
TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS645A-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS645A-1NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS645ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS645ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AS645DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS645A-1DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS645A-1NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74ALS645ADWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS645ANSR	SO	NS	20	2000	346.0	346.0	41.0
SN74AS645DWR	SOIC	DW	20	2000	346.0	346.0	41.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



IMPORTANT NOTICE

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